BQ25175 Standalone 1-Cell 800-mA Linear Battery Charger with 4.35-V Charge Voltage and Charging Indication

1 Features

- Input voltage up to 30-V tolerant
- Automatic Sleep Mode for low power consumption
  - 350-nA battery leakage current
  - 80-µA input leakage current when charge disabled
- Supports 1-cell Li-Ion, and Li-Poly
- Fixed 4.35-V battery regulation voltage
- External resistor programmable operation
  - ISET to set charge current from 10 mA to 800 mA
- High accuracy
  - ±0.5% charge voltage accuracy
  - ±10% charge current accuracy
- Charging features
  - Precharge current 20% of ISET
  - Termination current 10% of ISET
  - NTC thermistor input to monitor battery temperature
  - Cold and hot temperature charging disabled
  - Cool temperature charging at 20% of ISET
  - TS pin for charging function control
  - Open-drain output for status and fault indication
- Integrated fault protection
  - 6.6-V IN overvoltage protection
  - 1000-mA overcurrent protection
  - 125°C thermal regulation; 150°C thermal shutdown protection
  - OUT short-circuit protection
  - ISET pin short/open protection

2 Applications

- Smart trackers
- True wireless headsets
- Smart remote control
- Pulse oximeter
- Blood glucose monitor

3 Description

The BQ25175 is an integrated 800-mA linear charger for 1-cell Li-Ion and Li-Poly batteries. The device has a single power output that charges the battery. The system load can be placed in parallel with the battery, as long as the average system load does not prevent the battery from charging fully within the safety timer duration. When the system load is placed in parallel with the battery, the charge current is shared between the system and the battery.

The device has three phases for charging a Li-Ion/Li-Poly battery: precharge to recover a fully discharged battery, fast-charge constant current to supply the bulk of the charge, and voltage regulation to reach full capacity.

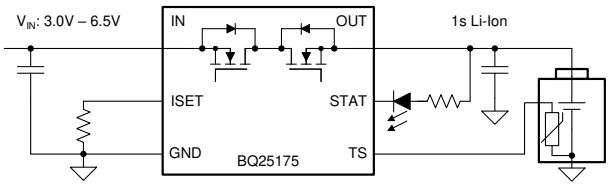
In all charge phases, an internal control loop monitors the IC junction temperature and reduces the charge current if an internal temperature threshold, T_{REG}, is exceeded.

The charger power stage and charge current sense functions are fully integrated. The charger function has high accuracy current and voltage regulation loops, charge status display, and automatic charge termination. The fast charge current is programmable through an external resistor. The precharge and termination current thresholds track the fast charge current setting.

Device Information

PART NUMBER(1)	PACKAGE	BODY SIZE (NOM)
BQ25175	DSBGA (6)	0.8 mm x 1.25 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.



Simplified Schematic

An IMPORTANT NOTICE at the end of this data sheet addresses availability, warranty, changes, use in safety-critical applications, intellectual property matters and other important disclaimers. PRODUCTION DATA.

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4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision * (June 2021) to Revision A (September 2021)	Page
• Changed from Advance Information to Production Data	1

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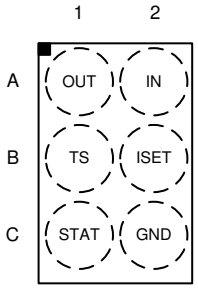
5 Pin Configuration and Functions



Top View = Xray through a soldered down part with A1 starting in upper left corner

Figure 5-1. YBG Package 6-Pin DSBGA Top View

Table 5-1. Pin Functions

PIN		I/O	DESCRIPTION
NAME	NO.		
OUT	A1	P	Battery connection. System load may be connected in parallel to battery. Bypass OUT with at least a 1-µF capacitor to GND, place close to the IC.
IN	A2	P	Input power, connected to external DC supply. Bypass IN with at least a 1-µF capacitor to GND, place close to the IC.
TS	B1	I	Temperature qualification voltage input. Connect a negative temperature coefficient (NTC) thermistor directly from TS to GND (AT103-2 recommended). Charge suspends when TS < V_{HOT} or TS > V_{COLD}. Charge at 20% of ISET when V_{COLD} > TS > V_{COOL}. If TS function is not needed, connect an external 10-kΩ resistor from this pin to GND. Pulling TS < V_{TS_ENZ} disables the charger.
ISET	B2	I	Programs the device fast-charge current. An external resistor from ISET to GND defines fast charge current value. Expected range is 30 kΩ (10 mA) to 375 Ω (800 mA). ICHG = K_{ISET} / R_{ISET}. Precharge current is defined as 20% of ICHG. Termination current is defined as 10% of ICHG.
STAT	C1	O	Open drain charger status indication output. Connect to pull-up rail via 10-kΩ resistor. LOW indicates charge in progress. HIGH indicates charge complete or charge disabled. When a fault condition is detected, the STAT pin blinks at 1 Hz. If unsued, this pin can be left floating.
GND	C2	–	Ground pin

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6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

		MIN	MAX	UNIT
Voltage	IN	–0.3	30	V
Voltage	OUT	–0.3	13	V
Voltage	ISET, STAT, TS	–0.3	5.5	V
T_J	Junction temperature	–40	150	°C
T_{stg}	Storage temperature	–65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Rating* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Condition*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

6.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001(1)	±2500	V
		Charged device model (CDM), per ANSI/ESDA/JEDEC JS-002(2)	±1500	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
V_{IN}	Input voltage	3.0		6.6	V
V_{OUT}	Output voltage			4.35	V
I_{OUT}	Output current			0.8	A
T_J	Junction temperature	–40		125	°C
C_{IN}	IN capacitor	1			µF
C_{OUT}	OUT capacitor	1			µF
R_{ISET}	ISET resistor	0.375		30	kΩ
R_{TS}	TS thermistor resistor (recommend 103AT-2)		10		kΩ

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6.4 Thermal Information

THERMAL METRIC[1]		BQ25175 YBG 6 PINS	UNIT
$R_{\theta JA}$	Junction-to-ambient thermal resistance (JEDEC[1])	132.4	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	1.5	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	36.9	°C/W
Ψ_{JT}	Junction-to-top characterization parameter	0.4	°C/W
Ψ_{JB}	Junction-to-board characterization parameter	36.9	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	N/A	°C/W

(1) For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.

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6.5 Electrical Characteristics

3.0V < V_{IN} < V_{IN_OV} and V_{IN} > V_{OUT} + V_{SLEEP}, T_J = -40°C to +125°C, and T_J = 25°C for typical values (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
QUIESCENT CURRENTS						
I_{Q_OUT}	Quiescent output current (OUT)	OUT= 4.2V, IN floating or IN = 0V - 5V, Charge Disabled, T_J = 25 °C		0.350	0.6	µA
		OUT= 4.2V, IN floating or IN = 0V - 5V, Charge Disabled, T_J < 105 °C		0.350	0.8	µA
$I_{SD_IN_TS}$	Shutdown input current (IN) with charge disabled via TS pin	IN = 5V, Charge Disabled (V_{TS} < V_{TS_ENZ}), no battery		80	110	µA
$I_{STANDBY_IN}$	Standby input current (IN) with charge terminated	IN = 5V, Charge Enabled, charge terminated		190		µA
I_{Q_IN}	Quiescent input current (IN)	IN = 5V, OUT = 3.8V, Charge Enabled, ICHG = 0A		0.45	0.6	mA
INPUT						
V_{IN_OP}	IN operating range		3.0		6.6	V
V_{IN_LOWV}	IN voltage to start charging	IN rising	3.05	3.09	3.15	V
V_{IN_LOWV}	IN voltage to stop charging	IN falling	2.80	2.95	3.10	V
V_{SLEEPZ}	Exit sleep mode threshold	IN rising, V_{IN} - V_{OUT}, OUT = 4V	95	135	175	mV
V_{SLEEP}	Sleep mode threshold hysteresis	IN falling, V_{IN} - V_{OUT}, OUT = 4V		80		mV
V_{IN_OV}	VIN overvoltage rising threshold	IN rising	6.60	6.75	6.90	V
V_{IN_OVZ}	VIN overvoltage falling threshold	IN falling		6.63		V
CONFIGURATION PINS SHORT/OPEN PROTECTION						
R_{ISET_SHORT}	Highest resistor value considered short	R_{ISET} below this at startup, charger does not initiate charge, power cycle or TS toggle to reset			350	Ω
BATTERY CHARGER						
V_{DO}	Dropout voltage (V_{IN} - V_{OUT})	VIN = 4.4V, IOUT = 300mA		425		mV
V_{REG_ACC}	OUT charge voltage accuracy	Tj = 25°C	4.328	4.350	4.3721	V
V_{REG_ACC}		Tj = -40°C to 125°C	4.306	4.350	4.393	V
I_{CHG_RANGE}	Typical charge current regulation range	V_{OUT} > V_{BAT_LOWV}	10		800	mA
K_{ISET}	Charge current setting factor, I_{CHG} = K_{ISET} / R_{ISET}	10mA < ICHG < 800mA	270	300	330	AΩ
I_{CHG_ACC}	Charge current accuracy	R_{ISET} = 375Ω, OUT = 3.8V	720	800	880	mA
		R_{ISET} = 600Ω, OUT = 3.8V	450	500	550	mA
		R_{ISET} = 3.0kΩ, OUT = 3.8V	90	100	110	mA
		R_{ISET} = 30kΩ, OUT = 3.8V	9	10	11	mA
I_{PRECHG}	Typical pre-charge current, as percentage of ICHG	V_{OUT} < V_{BAT_LOWV}		20		%
I_{PRECHG_ACC}	Precharge current accuracy	R_{ISET} = 375Ω, OUT = 2.5V	144	160	176	mA
		R_{ISET} = 600Ω, OUT = 2.5V	85	100	110	mA
		R_{ISET} = 3.0kΩ, OUT = 2.5V	18	20	22	mA
		R_{ISET} = 30kΩ, OUT = 2.5V	1.4	2	2.6	mA
I_{TERM}	Typical termination current, as percentage of ICHG	V_{OUT} = V_{REG}		10		%
I_{TERM_ACC}	Termination current accuracy	R_{ISET} = 600Ω	45	50	55	mA
		R_{ISET} = 3.0kΩ	8.5	10	11.5	mA
		R_{ISET} =30kΩ	0.4	1	1.6	mA

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6.5 Electrical Characteristics (continued)

3.0V < V_{IN} < V_{IN_OV} and V_{IN} > V_{OUT} + V_{SLEEP}, T_J = -40°C to +125°C, and T_J = 25°C for typical values (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{BAT_SHORT}	Output (OUT) short circuit voltage rising threshold, for Li-Ion chemistry	OUT rising	2.1	2.2	2.3	V
$V_{BAT_SHORT_HYS}$	Output (OUT) short circuit voltage hysteresis	OUT falling		200		mV
I_{BAT_SHORT}	OUT short circuit charging current	V_{OUT} < V_{BAT_SHORT}	4	6	8	mA
V_{BAT_LOWV}	Pre-charge to fast-charge transition threshold, for Li-Ion chemistry	OUT rising	2.7	2.8	3.0	V
$V_{BAT_LOWV_HYS}$	Battery LOWV hysteresis	OUT falling		100		mV
V_{RECHG}	Battery recharge threshold for Li-Ion chemistry	OUT falling V_{REG_ACC} - VOUT	75	100	125	mV
R_{ON}	Charging path FET on-resistance	VIN = 4.4V, IOUT = 300mA, T_J = 25°C		845	1000	mΩ
		VIN = 4.4V, IOUT = 300mA, T_J = -40 - 125°C		845	1450	mΩ
BATTERY CHARGER PROTECTION						
V_{OUT_OVP}	OUT overvoltage rising threshold	VOUT rising, as percentage of VREG	103	104	105	%
V_{OUT_OVP}	OUT overvoltage falling threshold	VOUT falling, as percentage of VREG	101	102	103	%
I_{OUT_OCP}	Output current limit threshold	IOUT rising	0.9	1	1.1	A
TEMPERATURE REGULATION AND TEMPERATURE SHUTDOWN						
T_{REG}	Typical junction temperature regulation			125		°C
T_{SHUT}	Thermal shutdown rising threshold	Temperature increasing		150		°C
	Thermal shutdown falling threshold	Temperature decreasing		135		°C
BATTERY-PACK NTC MONITOR						
I_{TS_BIAS}	TS nominal bias current		36.5	38	39.5	µA
V_{COLD}	Cold temperature threshold	TS pin voltage rising (approx. 0°C)	0.99	1.04	1.09	V
	Cold temperature exit threshold	TS pin voltage falling (approx. 4°C)	0.83	0.88	0.93	V
V_{COOL}	Normal to low temperature charge; Charge current target reduced to 20% x ISET	TS pin voltage rising (approx. 10°C)	650	680	710	mV
	Low temperature to normal charge; Charge current target returns to ISET	TS pin voltage falling (approx. 13°C)	580	610	640	mV
V_{HOT}	Hot temperature threshold	TS pin voltage falling (approx. 45°C)	176	188	200	mV
	Hot temperature exit threshold	TS pin voltage rising (approx. 40°C)	208	220	232	mV
V_{TS_ENZ}	Charge Disable threshold. Crossing this threshold shall shutdown IC	TS pin voltage falling	40	50	60	mV
V_{TS_EN}	Charge Enable threshold. Crossing this threshold shall restart IC operation	TS pin voltage rising	65	75	85	mV
V_{TS_CLAMP}	TS maximum voltage clamp	TS pin open-circuit (float)	2.3	2.6	2.9	V
LOGIC OUTPUT PIN (STAT)						
V_{OL}	Output low threshold level	Sink current = 5mA			0.4	V
I_{OUT_BIAS}	High-level leakage current	Pull up rail 3.3V			1	µA

6.6 Timing Requirements

		MIN	NOM	MAX	UNIT
BATTERY CHARGER					
$t_{TS_DUTY_ON}$	TS turn-on time during TS duty cycle mode		100		ms
$t_{TS_DUTY_OFF}$	TS turn-off time during TS duty cycle mode		2		s

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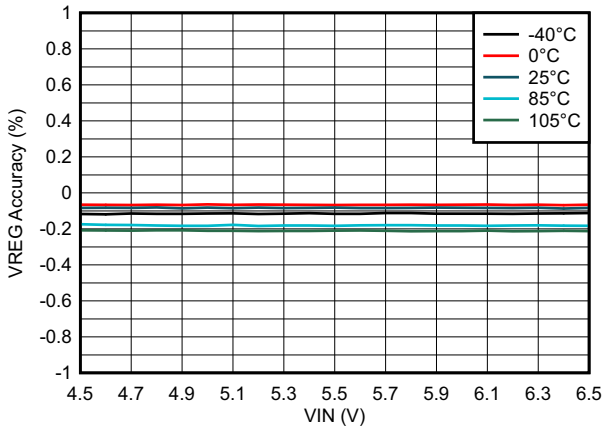
		MIN	NOM	MAX	UNIT
$t_{OUT_OCP_DGL}$	Deglitch time for I_{OUT_OCP}, IOUT rising		100		µs
t_{PRECHG}	Pre-charge safety timer accuracy	28.5	30	31.5	min
t_{SAFETY}	Fast-charge safety timer accuracy	9.5	10	10.5	hr

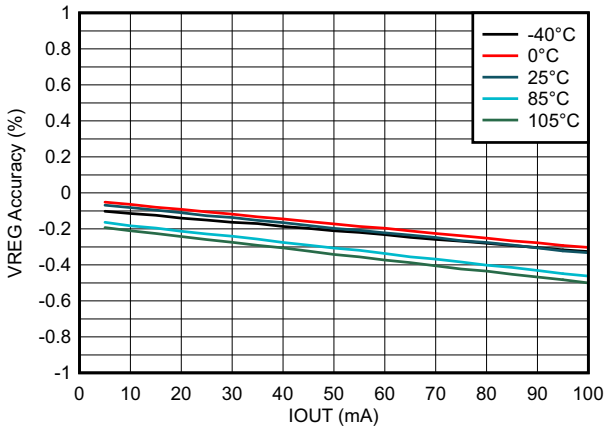
6.7 Typical Characteristics

C_{IN} = 1 µF, C_{OUT} = 1 µF



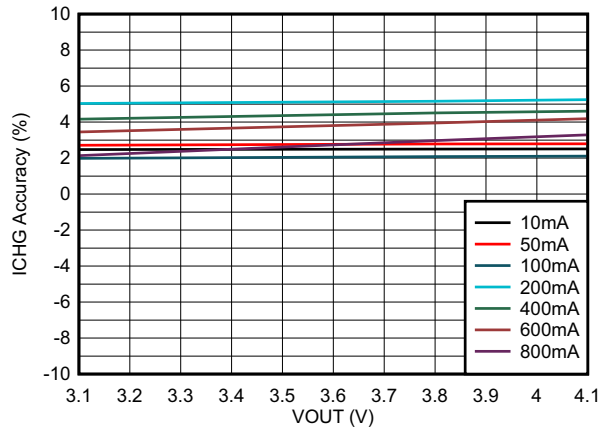
IOUT = 20 mA VOUT = 4.35 V

Figure 6-1. Line Regulation



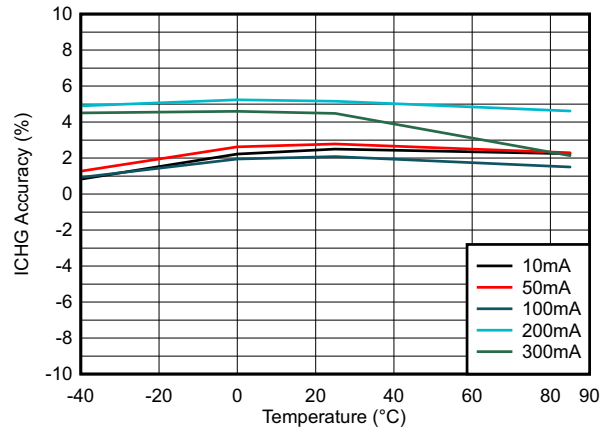
VIN = 5 V VOUT = 4.35 V

Figure 6-2. Load Regulation



VIN = 5 V Temp = 25ºC

Figure 6-3. ICHG Accuracy vs. V_{OUT}



VIN = 5 V VOUT = 3.8 V

Figure 6-4. ICHG Accuracy vs. Temperature

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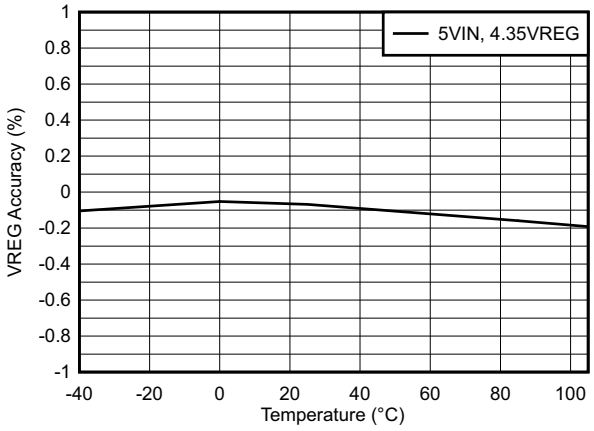
6.7 Typical Characteristics (continued)

C_{IN} = 1 µF, C_{OUT} = 1 µF



IOUT = 10 mA

Figure 6-5. VSET Accuracy vs. Temperature

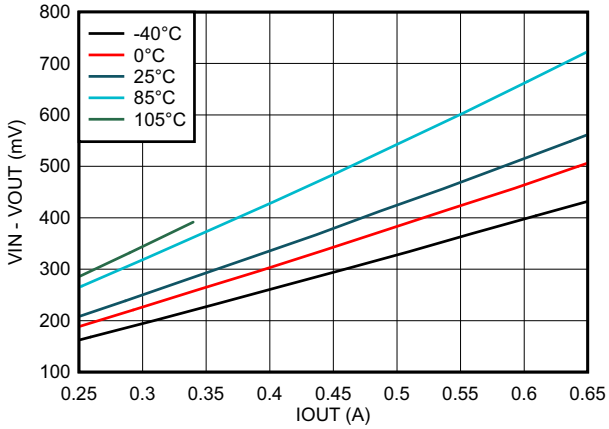
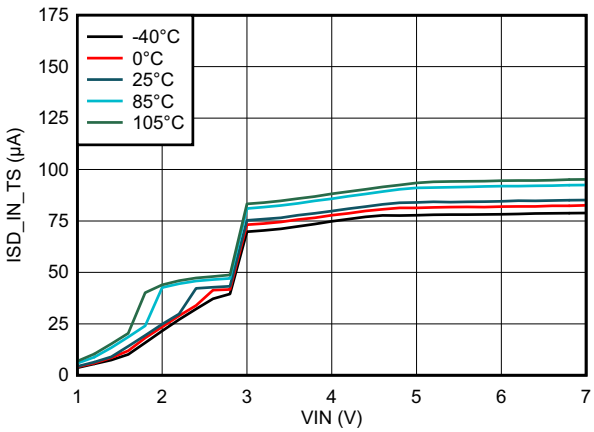
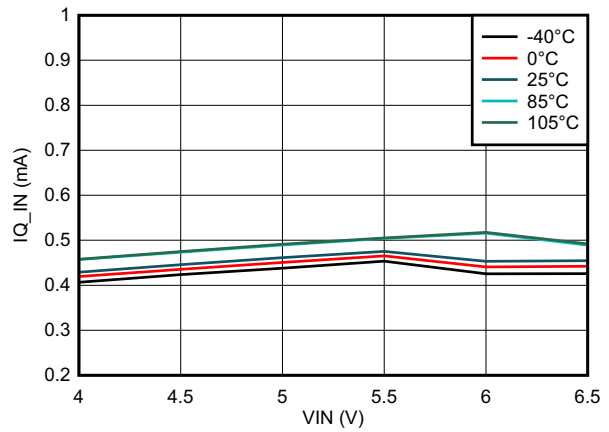


Figure 6-6. Dropout Voltage vs. Output Current



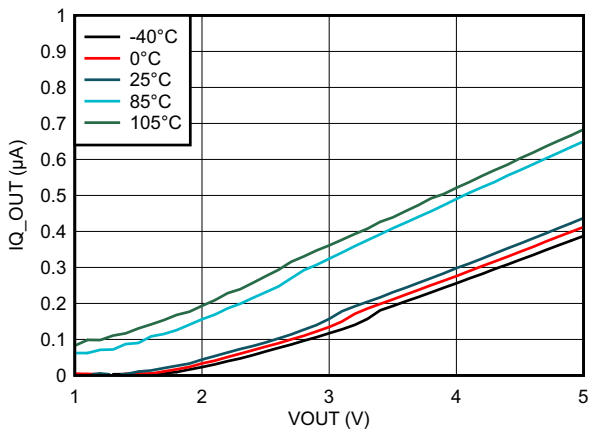
TS Pin = LOW VOUT = 0 V

Figure 6-7. Input Shutdown Current vs. Input Voltage



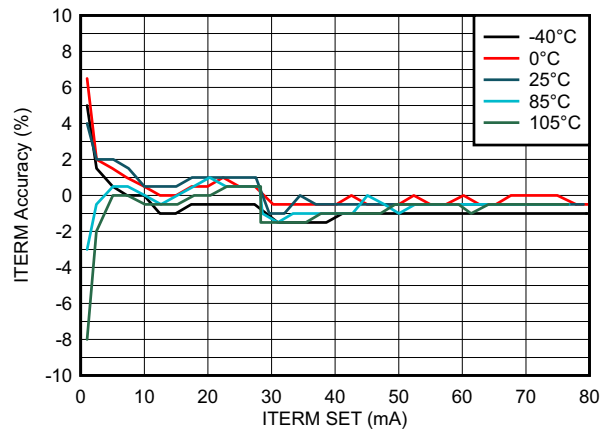
ICHG = 0 A VOUT = 0 V

Figure 6-8. Input Quiescent Current vs. Input Voltage



VIN = 0 V

Figure 6-9. Output Quiescent Current vs. Output Voltage



VIN = 5V VOUT = 4.35V

Figure 6-10. Termination Current Accuracy vs. Termination Current Setting

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7 Detailed Description

7.1 Overview

The BQ25175 is an integrated 800-mA linear charger for 1-cell Li-Ion/Li-Poly batteries. The device has a single power output that charges the battery. The system load can be placed in parallel with the battery, as long as the average system load does not prevent the battery from charging fully within the safety timer duration. When the system load is placed in parallel with the battery, the input current is shared between the system and the battery.

The device has three phases for charging a Li-Ion/Li-Poly battery: precharge to recover a fully discharged battery, fast-charge constant current to supply the bulk of the charge, and voltage regulation to reach full capacity.

The charger includes flexibility in programming of the fast-charge current. This charger is designed to work with a standard USB connection or dedicated charging adapter (DC output).

The charger also comes with a full set of safety features: battery temperature monitoring, overvoltage protection, charge safety timers, and configuration pin (ISET) short and open protection. All of these features and more are described in detail below.

The charger is designed for a single path from the input to the output to charge the battery. Upon application of a valid input power source, the configuration pins are checked for short/open circuit.

If the battery voltage is below the V_{BAT_LOWV} threshold, the battery is considered discharged and a preconditioning cycle begins. The amount of precharge current is 20% of the programmed fast-charge current via the ISET pin. The t_{PRECHG} safety timer is active, and stops charging after expiration if battery voltage fails to rise above V_{BAT_LOWV}.

Once the battery has charged to the V_{BAT_LOWV} threshold, Fast Charge Mode is initiated, applying the fast charge current and starting the t_{SAFETY} timer. The fast charge constant current is programmed using the ISET pin. The constant current phase provides the bulk of the charge. Power dissipation in the IC is greatest in fast charge with a lower battery voltage. If the IC temperature reaches T_{REG}, the IC enters thermal regulation, slows the timer clock by half, and reduces the charge current as needed to keep the temperature from rising any further. Figure 7-1 shows the typical lithium battery charging profile with thermal regulation. Under normal operating conditions, the IC junction temperature is less than T_{REG} and thermal regulation is not entered.

Once the battery has charged to the regulation voltage, the voltage loop takes control and holds the battery at the regulation voltage until the current tapers to the termination threshold. The termination threshold is 10% of the programmed fast-charge current.

Further details are described in Section 7.3.

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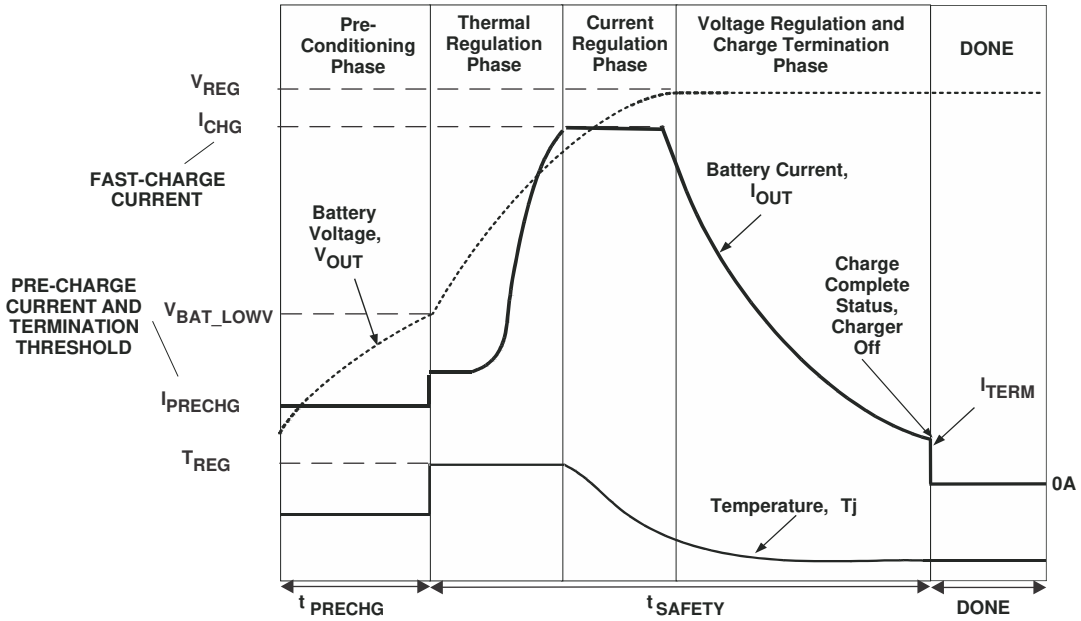
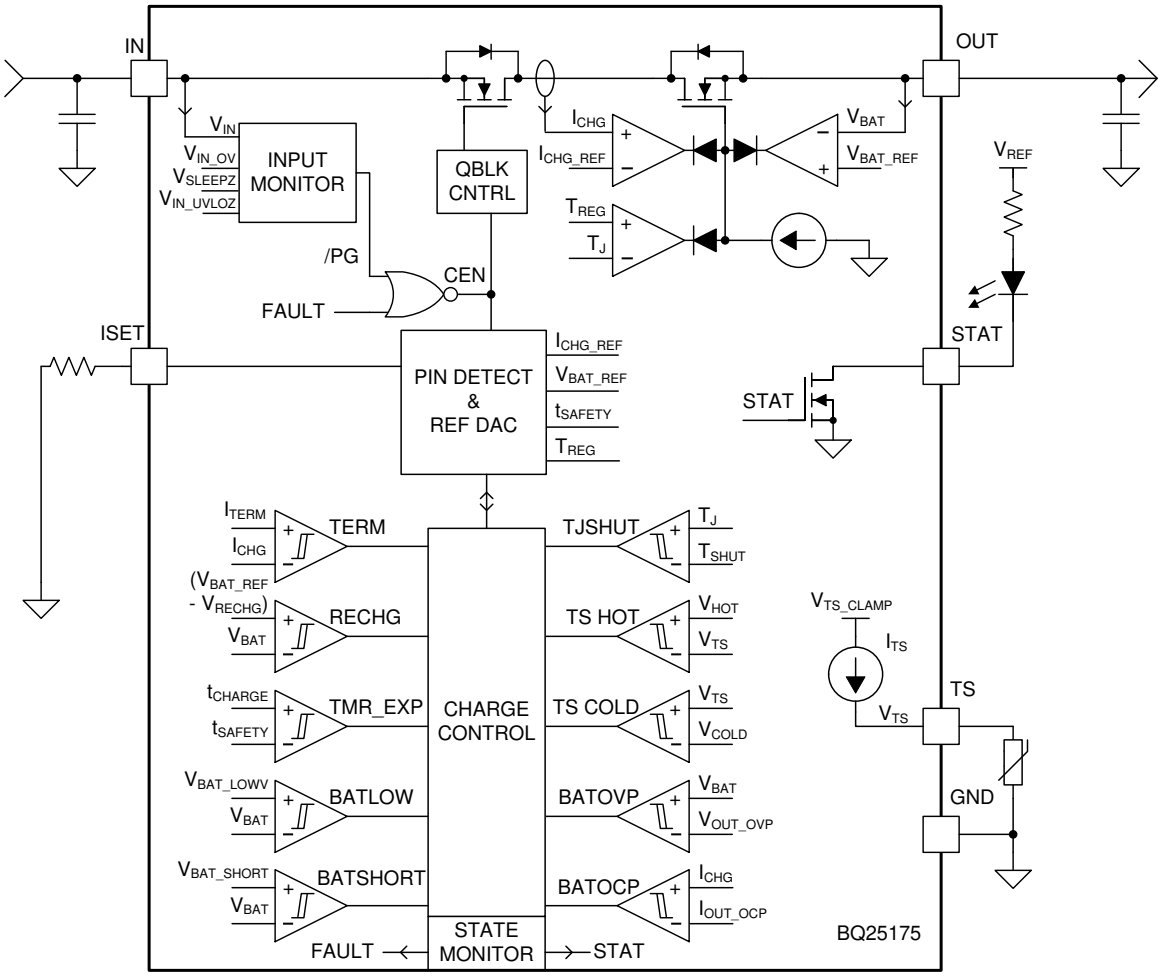


Figure 7-1. Lithium-Ion Battery Charging Profile with Thermal Regulation

7.2 Functional Block Diagram



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7.3 Feature Description

7.3.1 Device Power Up from Input Source

When an input source is plugged in and charge is enabled, the device checks the input source voltage to turn on all the bias circuits. It detects and sets the charge current and charge voltage limits before the linear regulator is started. The power up sequence from input source is as listed:

1. ISET pin detection
2. Charger power up

7.3.1.1 ISET Pin Detection

After a valid VIN is plugged in, the device checks the resistor on the ISET pin for a short circuit (R_{ISET} < R_{ISET_SHORT}). If a short condition is detected, the charger remains in the FAULT state until the input or TS pin is toggled. If the ISET pin is open-circuit, the charger proceeds through pin detection and starts the charger with no charge current. This pin is monitored while charging and changes in R_{ISET} while the charger is operating will immediately translate to changes in charge current.

An external pulldown resistor (±1% or better is recommended to minimize charge current error) from the ISET pin to GND sets the charge current as:

$$I_{CHG} = \frac{K_{ISET}}{R_{ISET}} \quad (1)$$

where:

- I_{CHG} is the desired fast-charge current
- K_{ISET} is a gain factor found in the electrical specifications
- R_{ISET} is the pulldown resistor from the ISET pin to GND

For charge currents below 50 mA, an extra RC circuit is recommended on ISET to achieve a more stable current signal. For greater accuracy at lower currents, part of the current-sensing FET is disabled to give better resolution.

7.3.1.2 Charger Power Up

After ISET pin resistor values have been validated, the device proceeds to enable the charger. The device automatically begins operation at the correct stage of battery charging depending on the OUT voltage.

7.3.2 Battery Charging Features

When charge is enabled, the device automatically completes a charging cycle according to the setting on the ISET pin without any intervention. The lithium-based charging cycle is automatically terminated when the charging current is below termination threshold, charge voltage is above recharge threshold, and device is not in thermal regulation (TREG). When a full battery is discharged below the recharge threshold (V_{RECHG}), the device automatically starts a new charging cycle. After charge is done, toggling the input supply or the TS pin can initiate a new charging cycle.

7.3.2.1 Lithium-Ion Battery Charging Profile

The device charges a lithium based battery in four phases: trickle charge, precharge, constant current, and constant voltage. At the beginning of a charging cycle, the device checks the battery voltage and regulates current and voltage accordingly.

If the charger is in thermal regulation during charging, the actual charging current is less than the programmed value. In this case, termination is temporarily disabled and the charging safety timer is counted at half the clock rate. For more information, refer to Section 7.3.2.3.

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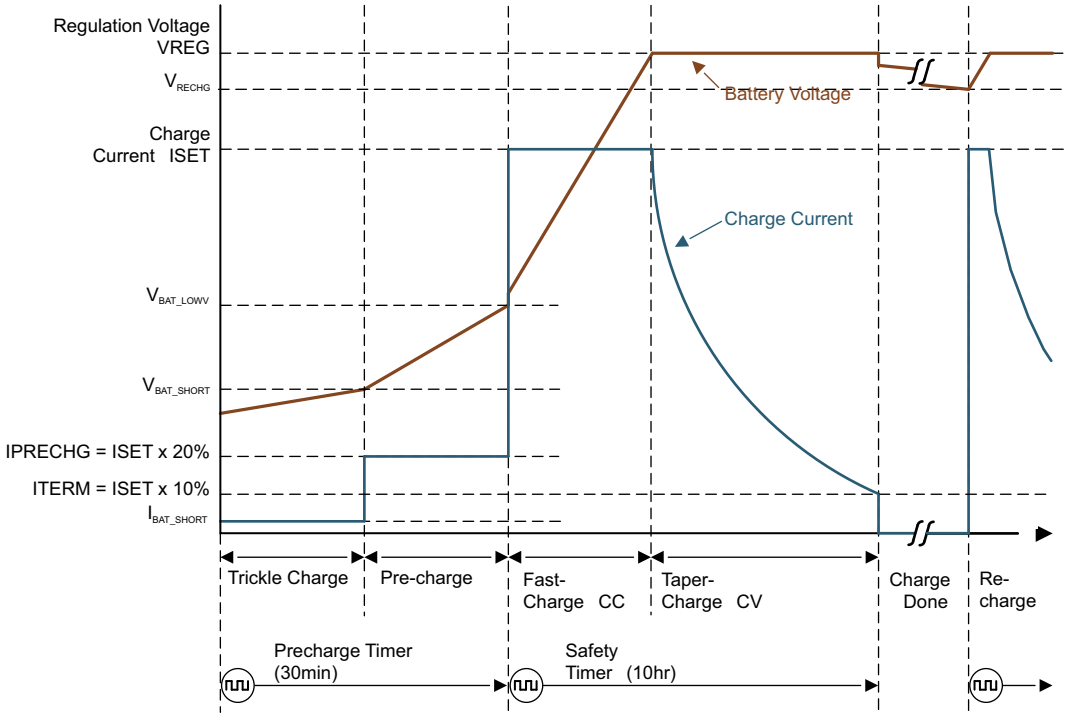

Figure 7-2. Battery Charging Profile

7.3.2.2 Charge Termination and Battery Recharge

The device terminates a charge cycle when the OUT pin voltage is above the recharge threshold (V_{RECHG}) and the current is below the termination threshold (I_{TERM}). Termination is temporarily disabled when the charger device is in thermal regulation. After charge termination is detected, the linear regulator turns off and the device enters the STANDBY state. Once the OUT pin drops below the V_{RECHG} threshold, a new charge cycle is automatically initiated.

7.3.2.3 Charging Safety Timers

The device has built-in safety timers to prevent an extended charging cycle due to abnormal battery conditions. The precharge timer is fixed at 30 minutes. The fast-charge safety timer is fixed at 10 hours. When the safety timer expires, the charge cycle ends. A toggle on the input supply or TS pin is required to restart a charge cycle after the safety timer has expired.

During thermal regulation, the safety timer counts at half the clock rate as the actual charge current is likely to be below the ISET setting. For example, if the charger is in thermal regulation throughout the whole charging cycle and the safety timer is 10 hours, then the timer will expire in 20 hours.

During faults which disable charging, such as VIN OVP, BAT OVP, TSHUT, or TS faults, the timer is suspended. Once the fault goes away, charging and the safety timer resume. If the charging cycle is stopped and started again, the timer gets reset (toggle of the TS pin restarts the timer).

The safety timer restarts counting for the following events:

1. Charging cycle stop and restart (toggle TS pin, charged battery falls below recharge threshold, or toggle input supply)
2. OUT pin voltage crosses the V_{BAT_LOWV} threshold in either direction

The precharge safety timer (fixed counter that runs when $V_{OUT} < V_{BAT_LOWV}$), follows the same rules as the fast-charge safety timer in terms of getting suspended, reset, and counting at half-rate.

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7.3.2.4 Battery Cold, Hot Temperature Qualification (TS Pin)

While charging, the device continuously monitors battery temperature by sensing the voltage at the TS pin. A negative temperature coefficient (NTC) thermistor should be connected between the TS and GND pins (recommend: 103AT-2). If temperature sensing is not required in the application, connect a fixed 10-kΩ resistor from TS to GND to allow normal operation. Battery charging is allowed when the TS pin voltage falls between the V_{COLD} and V_{HOT} thresholds (typically 0°C to 45°C). Charging current is reduced to 20% of the programmed ISET value when V_{COLD} > TS > V_{COOL} (typically 0°C to 10°C). The charging profile can be seen in Figure 7-3.

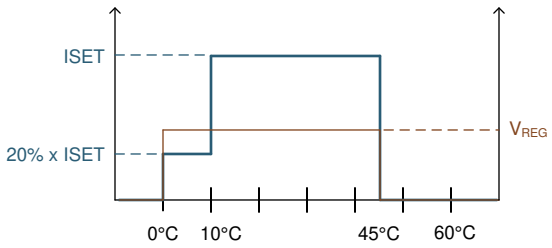

Figure 7-3. BQ25175 Charging Profile

If the TS pin indicates battery temperature is outside this range, the device stops charging, enters the STANDBY state, and blinks the STAT pin. Once battery temperature returns to normal conditions, charging resumes automatically.

In addition to battery temperature sensing, the TS pin can be used to disable the charger at any time by pulling TS voltage below V_{TS_ENZ}. The device disables the charger and consumes $I_{SD_IN_TS}$ from the input supply. In order to minimize quiescent current, the TS current source (I_{TS_BIAS}) is duty-cycled, with an on time of $t_{TS_DUTY_ON}$ and an off time of $t_{TS_DUTY_OFF}$. After the TS pin pulldown is released, the device may take up to $t_{TS_DUTY_OFF}$ to turn the I_{TS_BIAS} back on. After the source is turned on, the TS pin voltage will go above V_{TS_EN}, and re-enable the charger operation. The device treats this TS pin toggle as an input supply toggle, triggering a device power up from input source (see Section 7.3.1).

7.3.3 Status Outputs (STAT)

7.3.3.1 Charging Status Indicator (STAT)

The device indicates the charging state on the open-drain STAT pin. This pin can drive an LED.

Table 7-1. STAT Pin State

CHARGING STATE	STAT PIN STATE
Charge completed, charger in Sleep mode or charge disabled (V_{TS} < V_{TS_ENZ})	HIGH
Charge in progress (including automatic recharge)	LOW
Fault (VIN OVP, BAT OVP, BAT OCP, TS HOT, TS COLD, TMR_EXP, or ISET pin short)	BLINK at 1 Hz

7.3.4 Protection Features

The device closely monitors input and output voltages, as well as internal FET current and temperature for safe linear regulator operation.

7.3.4.1 Input Overvoltage Protection (VIN OVP)

If the voltage at the IN pin exceeds V_{IN_OV}, the device turns off after a deglitch, $t_{VIN_OV_DGL}$. The safety timer suspends counting and the device enters Standby mode. Once the IN voltage recovers to a normal level, the charge cycle and the safety timer automatically resume operation.

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7.3.4.2 Output Overvoltage Protection (BAT OVP)

If the voltage at the OUT pin exceeds V_{OUT_OVP}, the device immediately stops charging. The safety timer suspends counting and the device enters Standby mode. Once the OUT voltage recovers to a normal level, the charge cycle and the safety timer resume operation.

7.3.4.3 Output Overcurrent Protection (BAT OCP)

During normal operation, the OUT current should be regulated to the ISET programmed value. However, if a short circuit occurs on the ISET pin, the OUT current may rise to an unintended level. If the current at the OUT pin exceeds I_{OUT_OCP}, the device turns off after a deglitch, $t_{OUT_OCP_DGL}$. The safety timer resets the count, and the device remains latched off. An input supply or TS pin toggle is required to restart operation.

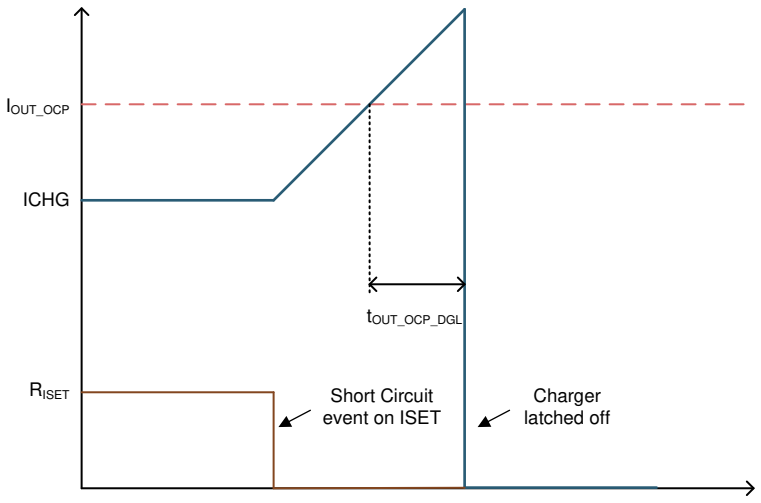

Figure 7-4. Overcurrent Protection

7.3.4.4 Thermal Regulation and Thermal Shutdown (TREG and TSHUT)

The device monitors its internal junction temperature (T_J) to avoid overheating and to limit the IC surface temperature. When the internal junction temperature exceeds the thermal regulation limit, the device automatically reduces the charge current to maintain the junction temperature at the thermal regulation limit (TREG). During thermal regulation, the actual charging current is usually below the programmed value on the ISET pin.

Therefore, the termination comparator for the Lithium-Ion battery is disabled, and the safety timer runs at half the clock rate.

Additionally, the device has thermal shutdown to turn off the linear regulator when the IC junction temperature exceeds the TSHUT threshold. The charger resumes operation when the IC die temperature decreases below the TSHUT falling threshold.

7.4 Device Functional Modes

7.4.1 Shutdown or Undervoltage Lockout (UVLO)

The device is in the shutdown state if the IN pin voltage is less than V_{IN_LOWV} or the TS pin is below V_{TS_ENZ}. The internal circuitry is powered down, all the pins are high impedance, and the device draws $I_{SD_IN_TS}$ from the input supply. Once the IN voltage rises above the V_{IN_LOW} threshold and the TS pin is above V_{TS_EN}, the IC enters Sleep mode or Active mode depending on the OUT pin voltage.

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7.4.2 Sleep Mode

The device is in Sleep mode when V_{IN_LOWV} < V_{IN} < V_{OUT} + V_{SLEEPZ} . The device waits for the input voltage to rise above V_{OUT} + V_{SLEEPZ} to start operation.

7.4.3 Active Mode

The device is powered up and charges the battery when the TS pin is above V_{TS_ENZ} and the IN voltage ramps above both V_{IN_LOWV} and V_{OUT} + V_{SLEEPZ}. The device draws I_{Q_IN} from the supply to bias the internal circuitry. For details on the device power-up sequence, refer to Section 7.3.1.

7.4.3.1 Standby Mode

The device is in Standby mode if a valid input supply is present and charge is terminated or if a recoverable fault is detected. The internal circuitry is partially biased, and the device continues to monitor for either VOUT to drop below V_{RECHG} or the recoverable fault to be removed.

7.4.4 Fault Mode

The fault conditions are categorized into recoverable and nonrecoverable as follows:

- Recoverable, from which the device should automatically recover once the fault condition is removed:
  - VIN OVP
  - BAT OVP
  - TS HOT
  - TS COLD
- Nonrecoverable, requiring pin or input supply toggle to resume operation:
  - BAT OCP
  - ISET pin short detected

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8 Application and Implementation

Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

8.1 Application Information

A typical application consists of the device configured as a standalone battery charger for single-cell Li-Ion or Li-Poly chemistries. The charge current is configured using a pulldown resistor on the ISET pin. A battery thermistor can be connected to the TS pin to allow the device to monitor battery temperature and control charging. Pulling the TS pin below V_{TS_ENZ} disables the charging function. Charger status is reported via the STAT pin.

8.2 Typical Applications

8.2.1 Li-Ion Charger Design Example

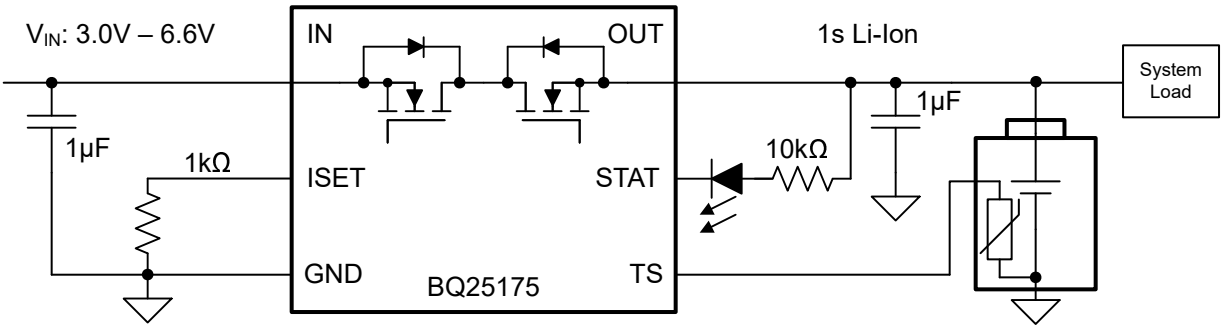

Figure 8-1. BQ25175 Typical Application for 1s Li-Ion Charging at 100 mA

8.2.1.1 Design Requirements

- Input supply up-to 6.6 V
- Battery is 1-cell Li-ion
- Fast charge current: I_{CHG} = 300 mA
- Charge voltage: V_{REG} = 4.35 V
- Termination current: I_{TERM} = 10% of I_{CHG} or 30 mA
- Precharge current: I_{PRECHG} = 20% of I_{CHG} or 60 mA
- TS – Battery temperature sense = 10-kΩ NTC (103AT)
  - Charging allowed between battery temperatures of 0ºC to 45ºC, with charge current reduction (I_{OUT} = 20% x I_{SET}) between 0ºC and 10ºC
- TS pin can be pulled low to disable charging or left floating to enable charging

8.2.1.2 Detailed Design Procedure

Regulation voltage is fixed to 4.35 V, input voltage is 5 V, and charge current is programmed via the ISET pin to 300 mA.

$R_{ISET} = [K_{ISET} / I_{CHG}]$
from the Electrical Characteristics table K_{ISET} = 300 AΩ
R_{ISET} = [300 AΩ/0.3 A] = 1000 Ω

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8.2.1.2.1 TS Function

Use a 10-kΩ NTC thermistor in the battery pack (recommend: 103AT-2). The V_{COLD} and V_{HOT} thresholds in this data sheet are designed to meet a charging window between 0°C and 45°C for a 10-kΩ NTC with β = 3435 K. To disable the TS sense function, use a fixed 10-kΩ resistor between the TS pin and GND. The TS pin can be pulled down to disable charging.

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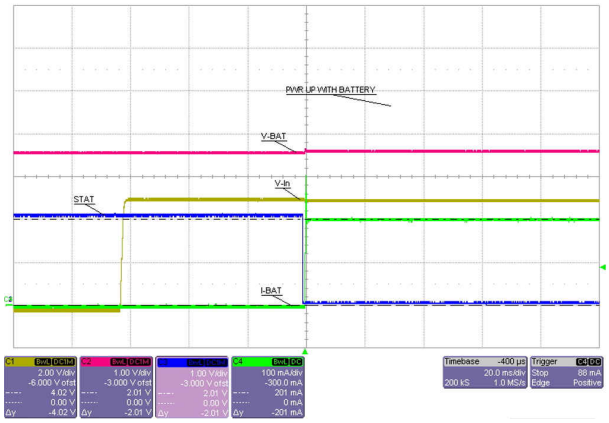
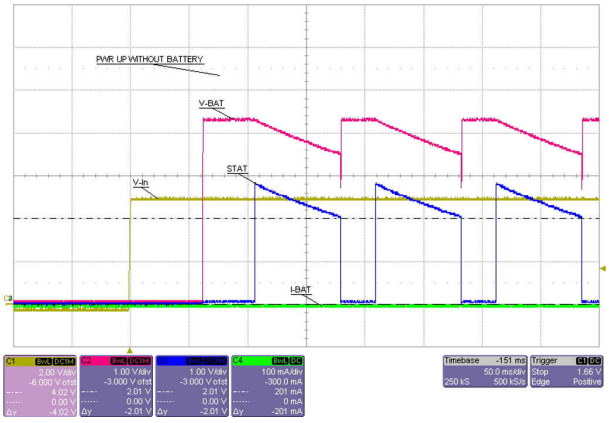
8.2.1.3 Application Curves

C_{IN} = 1 µF, C_{OUT} = 1 µF, V_{IN} = 5 V, I_{CHG} = 200 mA (unless otherwise specified)



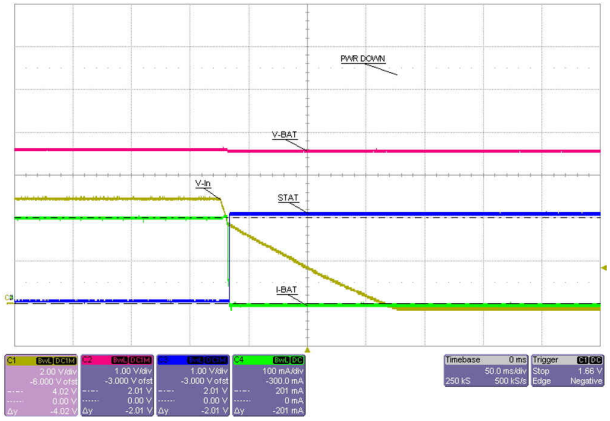
R_{ISET} = 1.2 kΩ

Figure 8-2. Power Up with Battery



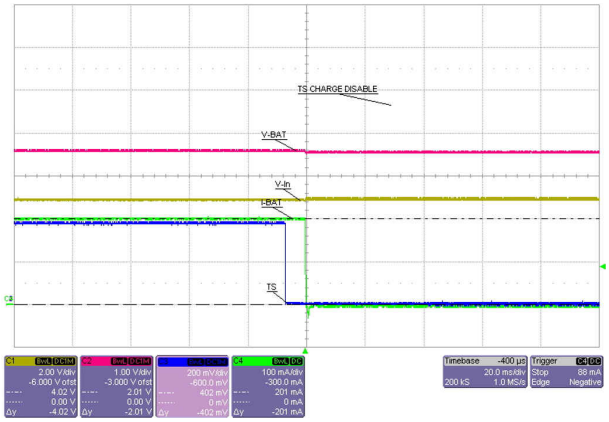
R_{ISET} = 1.2 kΩ OUT = open-circuit

Figure 8-3. Power Up without Battery



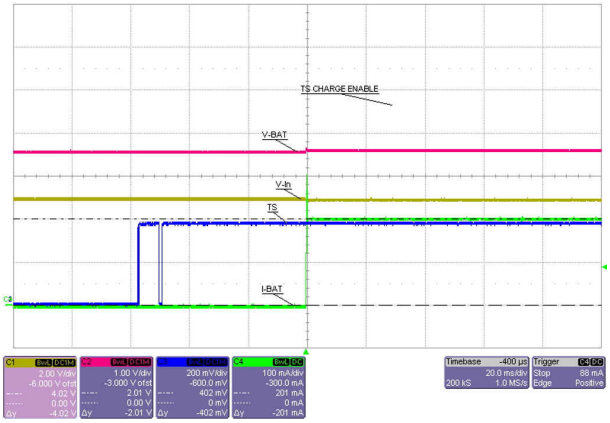
VIN = 5V → 0V

Figure 8-4. Power Down



TS pulled LOW

Figure 8-5. Charge Disable



TS pin released

Figure 8-6. Charge Enable

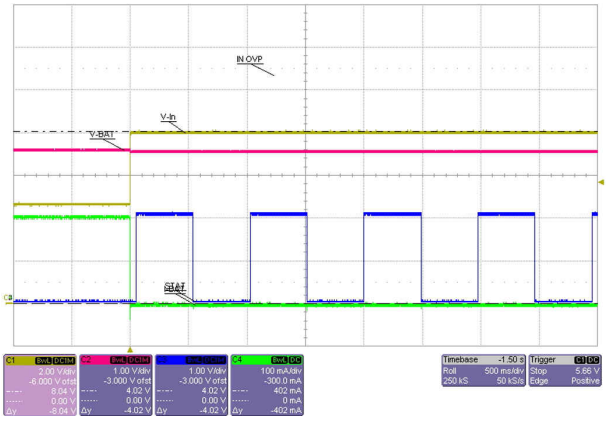


Figure 8-7. IN OVP Response

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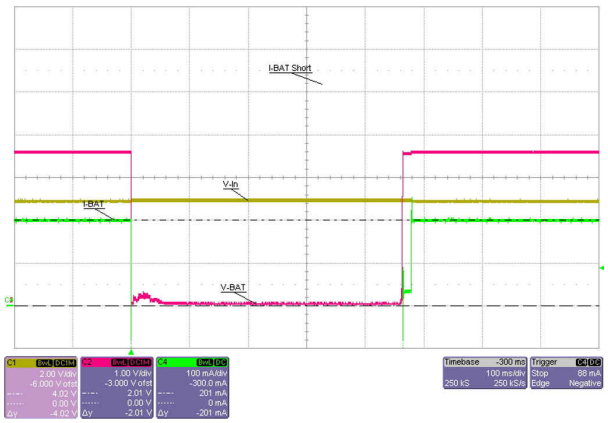
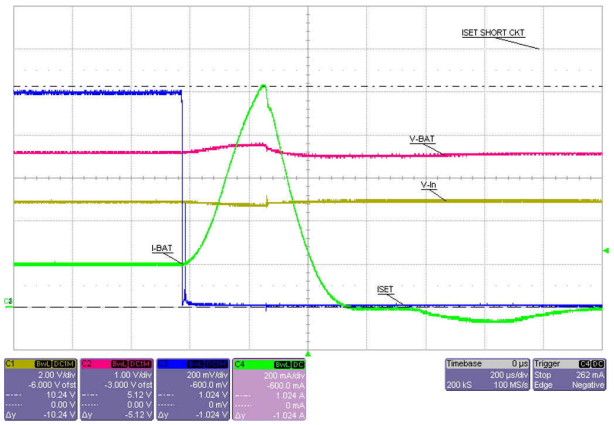


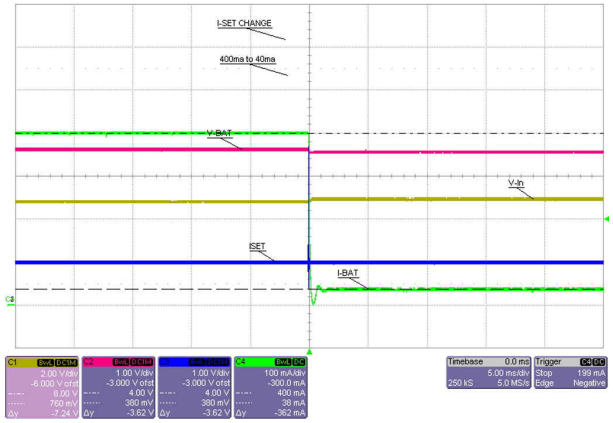
V_{OUT} = VREG = 3.5 V → 0 V

Figure 8-8. OUT Short-Circuit Response



I_{SET} = 1.5 kΩ → 0 Ω

Figure 8-9. ISET Short-Circuit Response



ISET = 400 mA → 40 mA

Figure 8-10. ISET Change Response

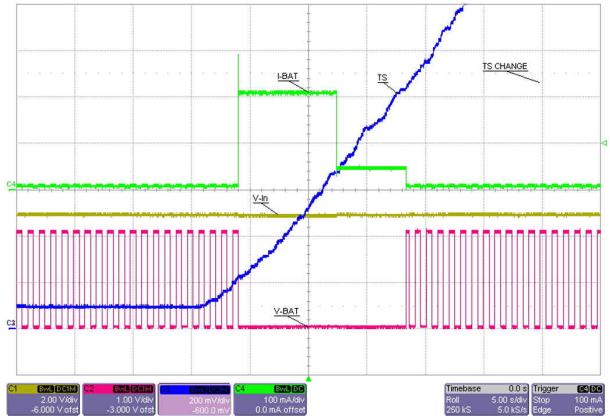


Figure 8-11. TS Change Response

9 Power Supply Recommendations

The device is designed to operate from an input voltage supply range between 3.0 V and 6.6 V (up to 30 V tolerant) and current capability of at least the maximum designed charge current. If located more than a few inches from the IN and GND pins, a larger capacitor is recommended.

10 Layout

10.1 Layout Guidelines

To obtain optimal performance, the decoupling capacitor from the IN pin to the GND pin and the output filter capacitor from the OUT pin to the GND pin should be placed as close as possible to the device, with short trace runs to both IN, OUT, and GND.

- All low-current GND connections should be kept separate from the high-current charge or discharge paths from the battery. Use a single-point ground technique incorporating both the small signal ground path and the power ground path.
- The high current charge paths into the IN pin and from the OUT pin must be sized appropriately for the maximum charge current in order to avoid voltage drops in these traces.

10.2 Layout Example

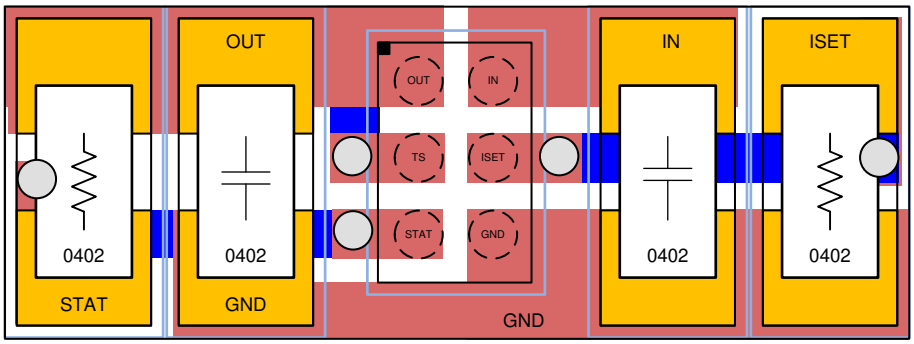


Figure 10-1. BQ25175 Board Layout Example

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11 Device and Documentation Support

11.1 Device Support

11.1.1 Third-Party Products Disclaimer

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11.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

11.6 Glossary

TI Glossary	This glossary lists and explains terms, acronyms, and definitions.

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12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
BQ25175YBGR	Active	Production	DSBGA (YBG) | 6	3000 | LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	B75
BQ25175YBGR.A	Active	Production	DSBGA (YBG) | 6	3000 | LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	B75

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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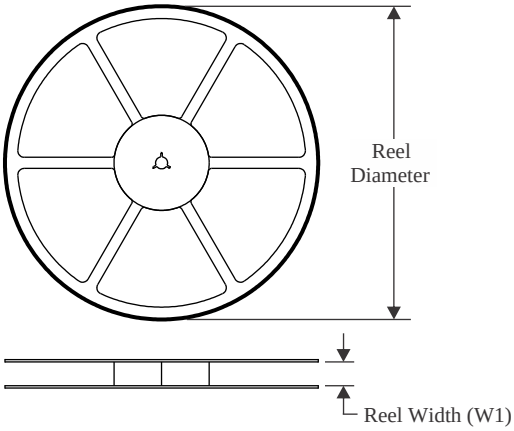
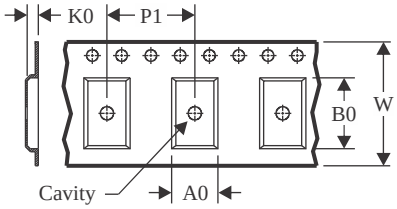
TAPE AND REEL INFORMATION

REEL DIMENSIONS

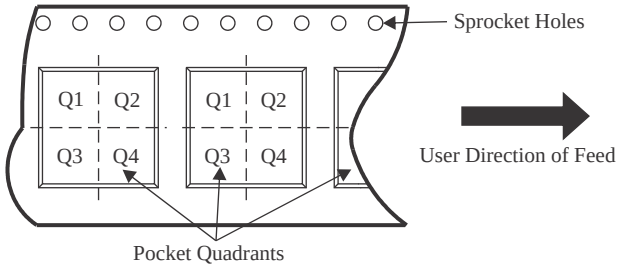


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

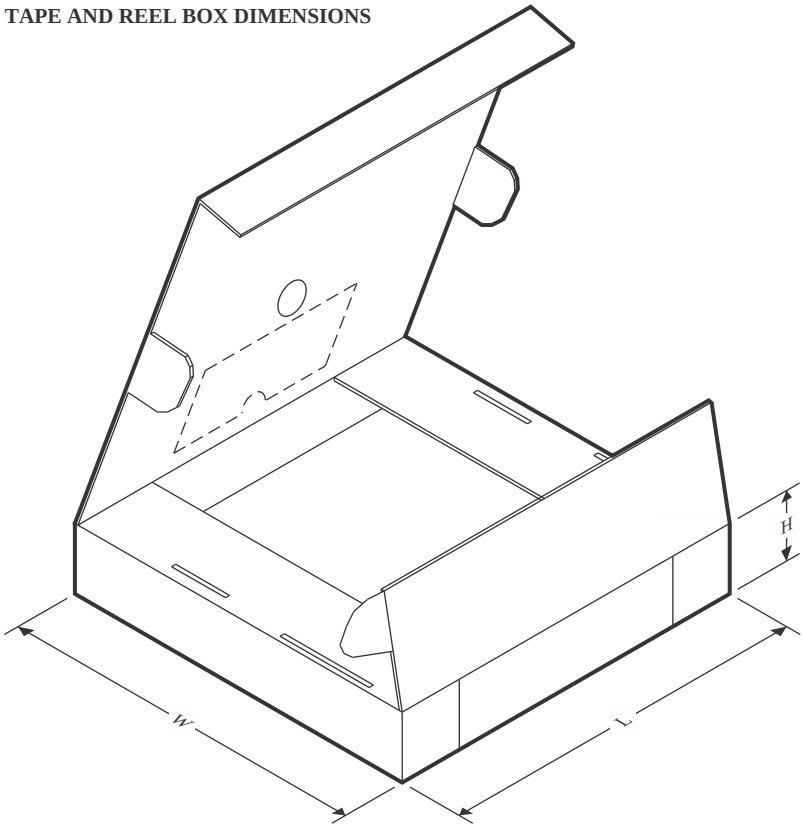
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
BQ25175YBGR	DSBGA	YBG	6	3000	180.0	8.4	0.92	1.26	0.55	2.0	8.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

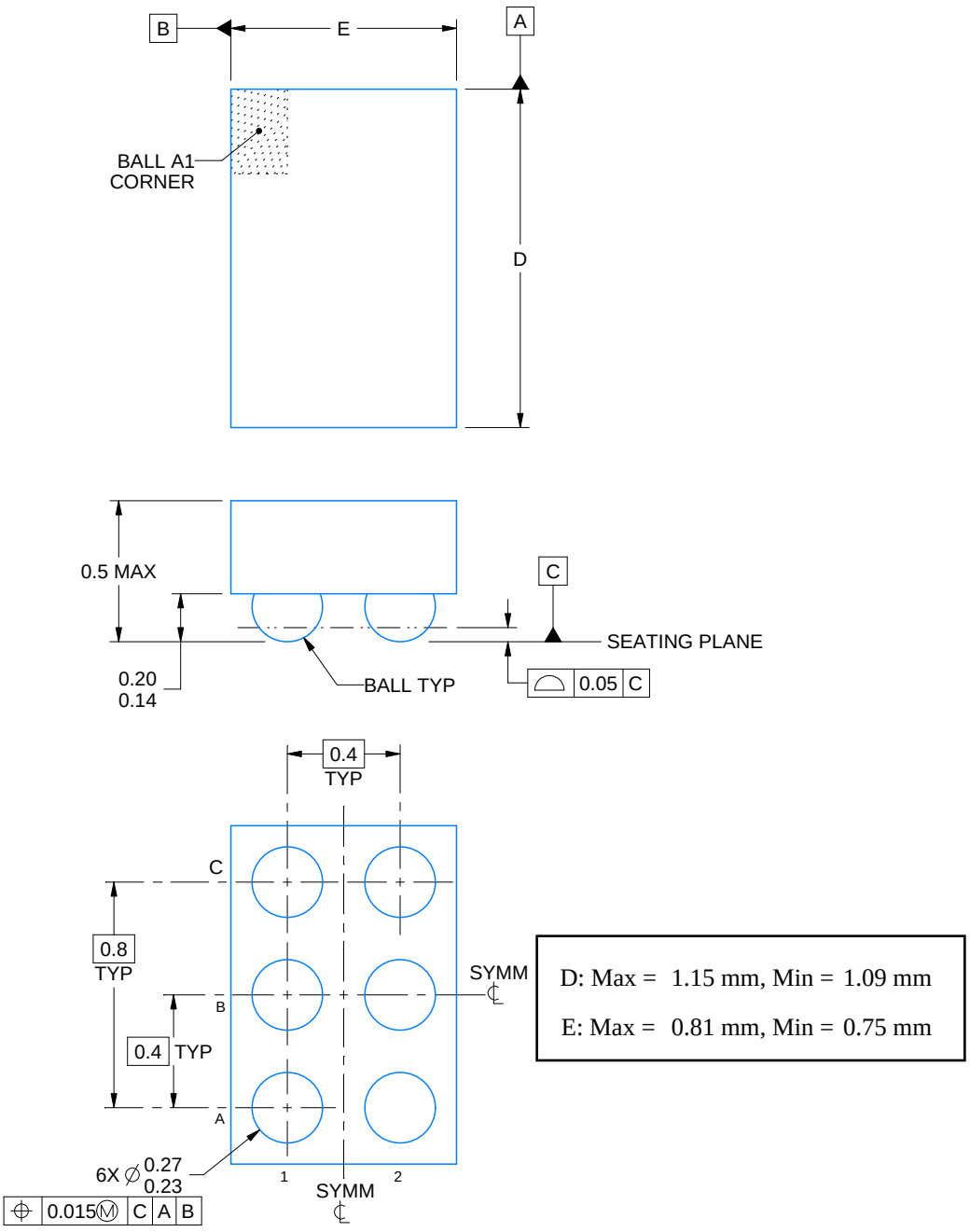
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
BQ25175YBGR	DSBGA	YBG	6	3000	182.0	182.0	20.0

PACKAGE OUTLINE

YBG0006

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



NOTES:

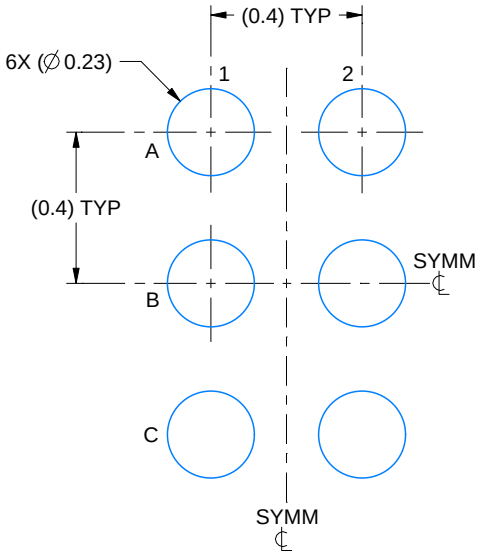
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

EXAMPLE BOARD LAYOUT

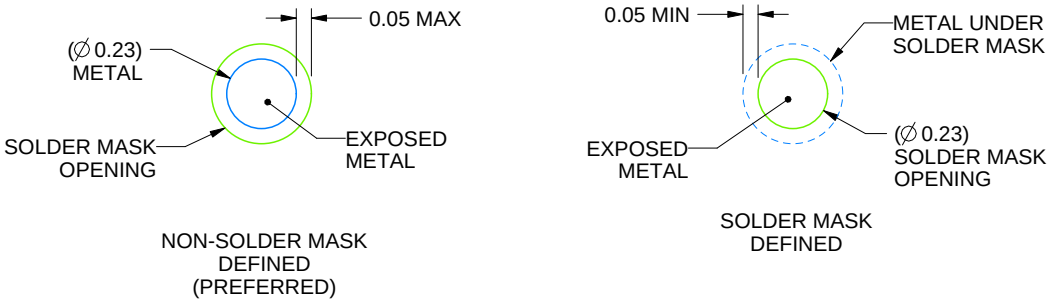
YBG0006

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 50X



SOLDER MASK DETAILS
NOT TO SCALE

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NOTES: (continued)

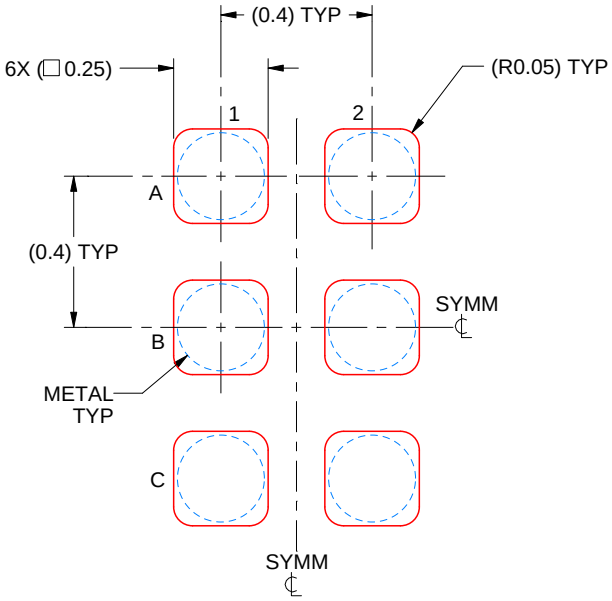
3. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints.
   See Texas Instruments Literature No. SNVA009 (www.ti.com/lit/snva009).

EXAMPLE STENCIL DESIGN

YBG0006

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL
SCALE: 50X

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NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

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